

GENERAL PROPERTIES

	PROPERTY	TYPICAL VALUE	DIRECTION	CONDITION	TEST METHOD
Thermal	Glass Transition Temperature, Tg	185	°C	A	DMA IPC-TM-650 2.4.24.2
		180	°C	A	DSC IPC-TM650 2.4.25
	Thermal Expansion, Z CTE	40	ppm/°C	A	Before Tg, IPC-TM-650 2.4
		210	ppm/°C	A	After Tg, IPC-TM-650 2.4
	Decomposition Temperature, Td	355	°C	A	TMA IPC-TM650 2.4.24.6
	Delamination Time, T260	60	minutes	A	TMA IPC-TM650 2.4.24
	Delamination Time, T288	30	minutes	A	TMA IPC-TM650 2.4.24
	Delamination Time, T300	15	minutes	A	TMA IPC-TM650 2.4.24
Electrical	Dielectric Constant (Dk)	4.90	-	1 MHz	IPC-TM-650 2.5.5.9
	Dissipation Factor (Df)	0.0180	-	1 MHz	IPC-TM-650 2.5.5.9
	Volume Resistivity	2.20E+08	MΩ·cm	After moisture resistance	IPC-TM-650 2.5.17.1
	Surface Resistivity	7.90E+07	MΩ	After moisture resistance	IPC-TM-650 2.5.17.1
	Dielectric Breakdown	45+NB	kV	D-48/50+D-0.5/23	IPC-TM-650 2.5.6
Physical	Thermal Conductivity	0.62	W/m·K	100°C	ASTM D5470
	Water Absorption	0.08	%	D-24/23	IPC-TM-650 2.6.2.1
	Copper Peel Strength	1.40(8.0)	N/mm (lb/in.)	after solder float 1 oz. EDC Foil	IPC-TM-650 2.4.8
	Flammability	94V-0	-	A	UL

PRODUCT CONTACTS

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